

# BIPOLAR ANALOG INTEGRATED CIRCUIT $\mu$ PC4741

# HIGH PERFORMANCE QUAD OPERATIONAL AMPLIFIER

#### **DESCRIPTION**

The  $\mu$ PC4741 consists of four independent frequency compensated operational amplifiers featuring higher speed, broader band than general purpose type as 741. The  $\mu$ PC4741 is most appropriate for AC signal amplifier applications such as active filters or pulse amplifiers.

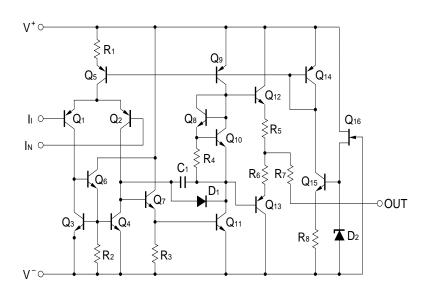
#### **FEATURES**

- Internal frequency compensation
- · Low noise
- · Output short circuit protection

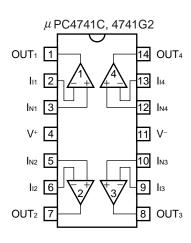
#### **ORDERING INFORMATION**

Part Number	Package
μPC4741C	14-pin plastic DIP (7.62 mm (300))
μPC4741C(5)	14-pin plastic DIP (7.62 mm (300))
μPC4741G2	14-pin plastic SOP (5.72 mm (225))
μPC4741G2(5)	14-pin plastic SOP (5.72 mm (225))

# **EQUIVALENT CIRCUIT (1/4 Circuit)**



# PIN CONFIGURATION (Top View)



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Not all products and/or types are available in every country. Please check with an NEC Electronics sales representative for availability and additional information.

# ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Parameter		Symbol	Ratings	Unit
Voltage between V <sup>+</sup> and V <sup>−</sup> Note1		V <sup>+</sup> – V <sup>-</sup>	-0.3 to +40	V
Differential Input Volta	ıge	VID	±30	V
Input Voltage Note2		Vı	V <sup>-</sup> −0.3 to V <sup>+</sup> +0.3	V
Output Voltage Note3		Vo	V <sup>-</sup> −0.3 to V <sup>+</sup> +0.3	V
Power Dissipation C Package Note4		Рт	570	mW
	G2 Package Note5		550	mW
Output Short Circuit Duration Note6			10	sec
Operating Ambient Temperature		TA	-20 to +80	°C
Storage Temperature		T <sub>stg</sub>	−55 to +125	°C

- **Notes 1.** Reverse connection of supply voltage can cause destruction.
  - 2. The input voltage should be allowed to input without damage or destruction. Even during the transition period of supply voltage, power on/off etc., this specification should be kept. The normal operation will establish when the both inputs are within the Common Mode Input Voltage Range of electrical characteristics.
  - 3. This specification is the voltage which should be allowed to supply to the output terminal from external without damage or destructive. Even during the transition period of supply voltage, power on/off etc., this specification should be kept. The output voltage of normal operation will be the Output Voltage Swing of electrical characteristics.
  - **4.** Thermal derating factor is –7.6 mW/°C when ambient temperature is higher than 50°C.
  - 5. Thermal derating factor is -5.5 mW/°C when ambient temperature is higher than 25°C.
  - **6.** Pay careful attention to the total power dissipation not to exceed the absolute maximum ratings, Note 4 and Note 5.

#### RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	$V^\pm$	±4		±16	٧

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# μPC4741C, 4741G2

# ELECTRICAL CHARACTERISTICS (TA = 25°C, $V^{\pm}$ = $\pm 15$ V)

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
	Input Offset Voltage	Vio	Rs ≤ 100 Ω		±1.0	±5.0	mV
	Input Offset Current Note	lio			±30	±50	nA
	Input Bias Current Note	Ів			70	300	nA
	Large Signal Voltage Gain	Av	$R_L \ge 2 \ k\Omega$ , $V_O = \pm 10 \ V$	25,000	50,000		
*	Power Consumption	Pd	lo = 0 A		150	210	mW
	Common Mode Rejection Ratio	CMR		80	100		dB
	Supply Voltage Rejection Ratio	SVR			50	100	μV/ V
	Maximum Output Voltage	Vom	$R_L \ge 10 \ k\Omega$	±12	±13.7		V
	Maximum Output Voltage	Vom	$R_L \geq 2 \; k\Omega$	±10	±12.5		V
	Common Mode Input Voltage Range	Vісм		±12	±14		V
	Slew Rate	SR	Av = 1		1.6		V/ μs
	Input Equivalent Noise Voltage Density	<b>e</b> n	f = 1 kHz		9		nV/√Hz
	Channel Separation		f = 10 kHz		108		dB

Note Input bias currents flow out from IC. Because each currents are base current of PNP-transistor on input stage.

# μPC4741C (5), 4741G2 (5)

# ELECTRICAL CHARACTERISTICS (TA = 25°C, $V^{\pm}$ = $\pm 15$ V)

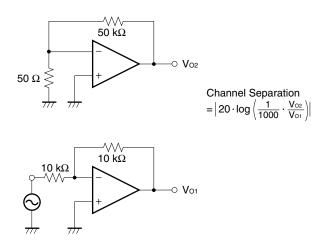
	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
	Input Offset Voltage	Vio	Rs ≤ 100 Ω		±1.0	±2.0	mV
	Input Offset Current Note	lio			±30	±50	nA
	Input Bias Current Note	Ів				100	nA
	Large Signal Voltage Gain	Av	$R_L \ge 2 \ k\Omega$ , $V_0 = \pm 10 \ V$	28,000	50,000		
*	Power Consumption	Pd	Io = 0 A		150	210	mW
	Common Mode Rejection Ratio	CMR		85	90		dB
	Supply Voltage Rejection Ratio	SVR				50	μV/ V
	Maximum Output Voltage	Vom	$R_L \ge 10 \text{ k}\Omega$	±12.5	±13.7		V
	Maximum Output Voltage	Vom	$R_L \ge 2 \ k\Omega$	±11	±12.5		V
	Common Mode Input Voltage Range	Vісм		±13	±14		V
	Slew Rate	SR	Av = 1		1.6		V/ μs
	Input Equivalent Noise Voltage Density	<b>e</b> n	f = 1 kHz		9		nV/√Hz
	Channel Separation		f = 10 kHz		108		dB

**Note** Input bias currents flow out from IC. Because each currents are base current of PNP-transistor on input stage.

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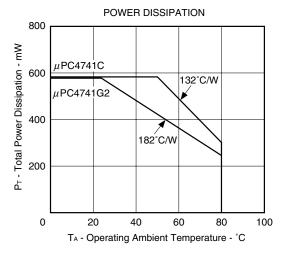
# **MEASUREMENT CIRCUIT**

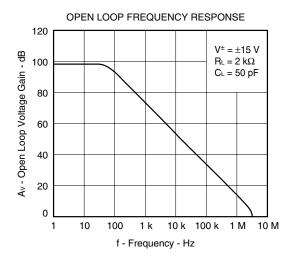
Fig.1 Channel Separation Measurement Circuit

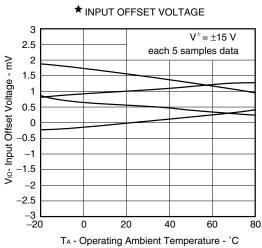


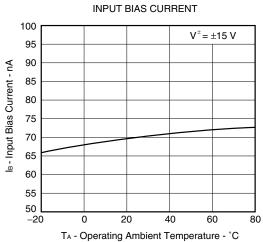


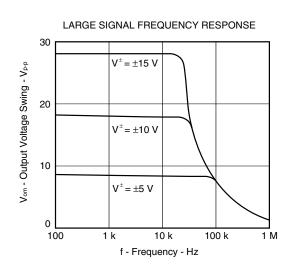
# TYPICAL PERFORMANCE CHARACTERISTICS (TA = 25°C, TYP.)

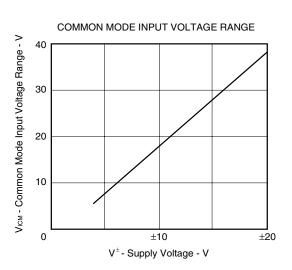




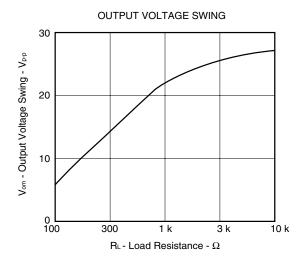


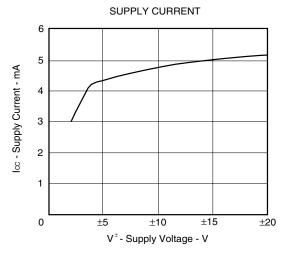


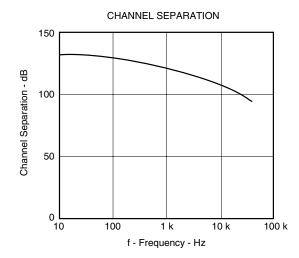


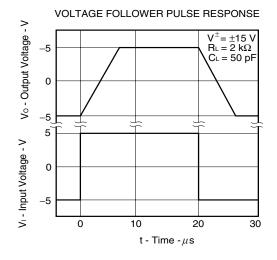


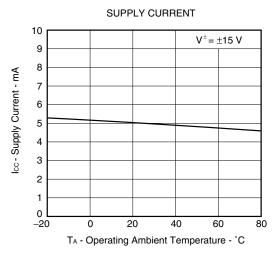
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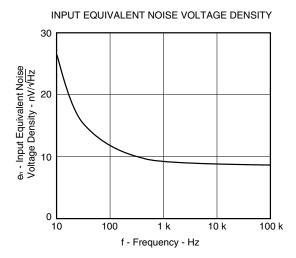






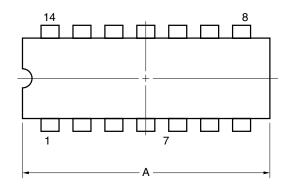


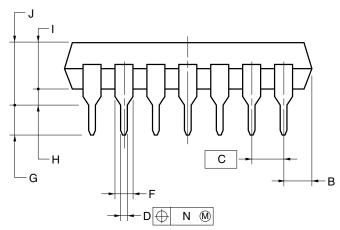


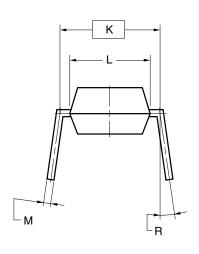


# PACKAGE DRAWINGS (Unit: mm)

# 14-PIN PLASTIC DIP (7.62 mm (300))







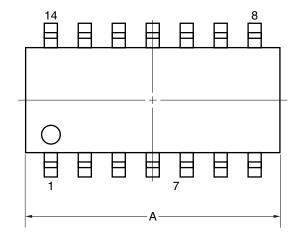
# NOTES

- Each lead centerline is located within 0.25 mm of its true position (T.P.) at maximum material condition.
- 2. Item "K" to center of leads when formed parallel.

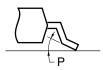
ITEM	MILLIMETERS
Α	19.22±0.2
В	2.14 MAX.
С	2.54 (T.P.)
D	0.50±0.10
F	1.32±0.12
G	3.6±0.3
Н	0.51 MIN.
I	3.55
J	4.3±0.2
K	7.62 (T.P.)
L	6.4±0.2
М	$0.25^{+0.10}_{-0.05}$
N	0.25
R	0~15°

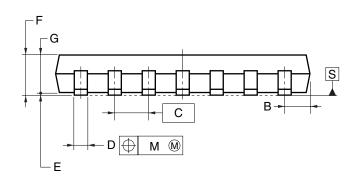
P14C-100-300B1-3

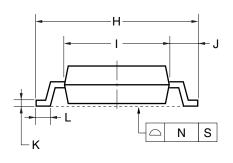
# 14-PIN PLASTIC SOP (5.72 mm (225))



detail of lead end







#### NOTE

Each lead centerline is located within 0.1 mm of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS
Α	10.2±0.26
В	1.42 MAX.
С	1.27 (T.P.)
D	$0.42^{+0.08}_{-0.07}$
Е	0.1±0.1
F	$1.59^{+0.21}_{-0.2}$
G	1.49
Н	6.5±0.2
ı	4.4±0.1
J	1.1±0.16
K	$0.17^{+0.08}_{-0.07}$
L	0.6±0.2
М	0.1
N	0.10
Р	3°+7°

S14GM-50-225B, C-6



# **★** RECOMMENDED SOLDERING CONDITIONS

The  $\mu PC4741$  should be soldered and mounted under the following recommended conditions.

For soldering methods and conditions other than those recommended below, contact an NEC Electronics sales representative.

For technical information, see the following website.

Semiconductor Device Mount Manual (http://www.necel.com/pkg/en/mount/index.html)

# **Type of Surface Mount Device**

μPC4741G2, 4741G2(5): 14-pin plastic SOP (5.72 mm (225))

Process	Conditions	Symbol
Infrared Ray Reflow	Peak temperature: 235°C or below (Package surface temperature), Reflow time: 30 seconds or less (at 210°C or higher), Maximum number of reflow processes: 3 time.	IR35-00-3
Vapor Phase Soldering	Peak temperature: 215°C or below (Package surface temperature), Reflow time: 40 seconds or less (at 200°C or higher), Maximum number of reflow processes: 3 time.	VP15-00-3
Wave Soldering	Solder temperature: 260°C or below, Flow time: 10 seconds or less,  Maximum number of flow processes: 1 time,  Pre-heating temperature: 120°C or below (Package surface temperature).	WS60-00-1
Partial Heating Method	Pin temperature: 300°C or below, Heat time: 3 seconds or less (Per each side of the device).	-

Caution Apply only one kind of soldering condition to a device, except for "partial heating method", or the device will be damaged by heat stress.

### Type of Through-hole Device

μPC4741C, 4741C(5): 14-pin plastic DIP (7.62 mm (300))

Process	Conditions	
Wave Soldering (only to leads)	Solder temperature: 260°C or below, Flow time: 10 seconds or less.	
Partial Heating Method	Pin temperature: 300°C or below, Heat time: 3 seconds or less (per each lead).	

Caution For through-hole device, the wave soldering process must be applied only to leads, and make sure that the package body does not get jet soldered.

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